



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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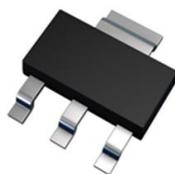
Features

- $BV_{CEO} > 30V$
- $I_C = 1A$ High Continuous Current
- $I_{CM} = 4A$ Peak Pulse Current
- Low Saturation Voltage
- Complementary PNP Type: NK-FZT589

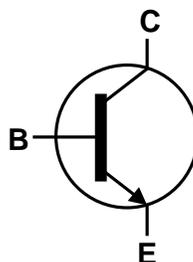
Mechanical Data

- Case: SOT223
- Case material: Molded Plastic. "Green" Molding Compound; UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 Ⓔ
- Weight: 0.112 grams (Approximate)

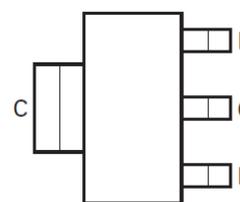
SOT223



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	50	V
Collector-Emitter Voltage	V _{CEO}	30	V
Emitter-Base Voltage	V _{EBO}	7	V
Continuous Collector Current	I _C	1	A
Base Current	I _B	200	mA
Peak Pulse Current	I _{CM}	4	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

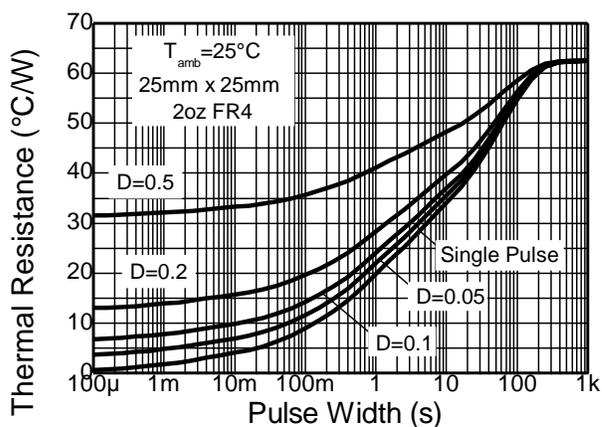
Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 6)	P _D	3.0	W
	(Note 7)		2.0	
	(Note 8)		1.6	
	(Note 9)		1.2	
Thermal Resistance, Junction to Ambient	(Note 6)	R _{θJA}	41.7	°C/W
	(Note 7)		62.5	
	(Note 8)		78.1	
	(Note 9)		104	
Thermal Resistance Junction to Lead	(Note 10)	R _{θJL}	19.4	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 11)

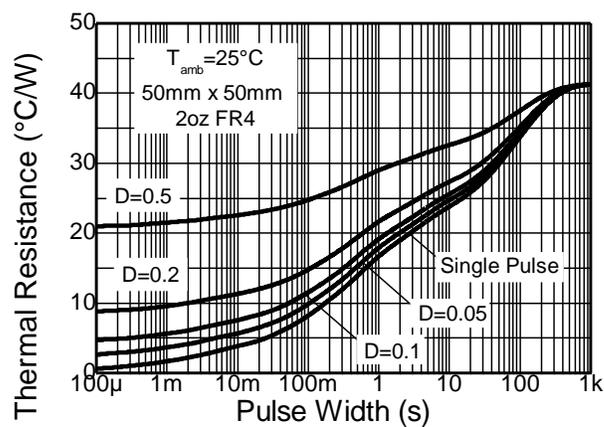
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 7. Same as Note 6, except the device is mounted on 25mm x 25mm 2oz copper.
 8. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
 9. Same as Note 6, except the device is mounted on minimum recommended pad layout.
 10. Thermal resistance from junction to solder-point (at the end of the collector lead).
 11. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

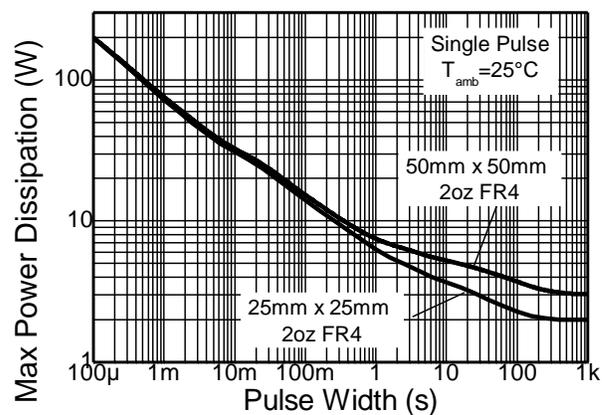
Thermal Characteristics and Derating Characteristics



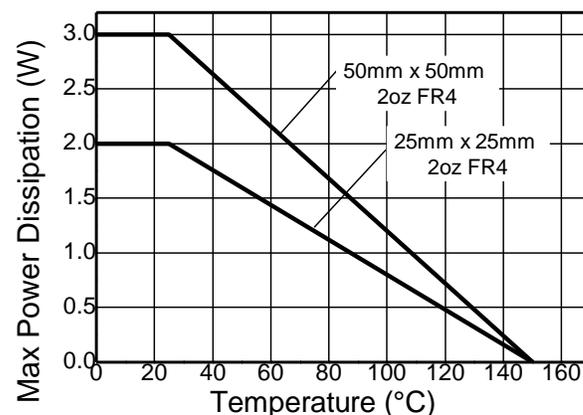
Transient Thermal Impedance



Transient Thermal Impedance



Pulse Power Dissipation



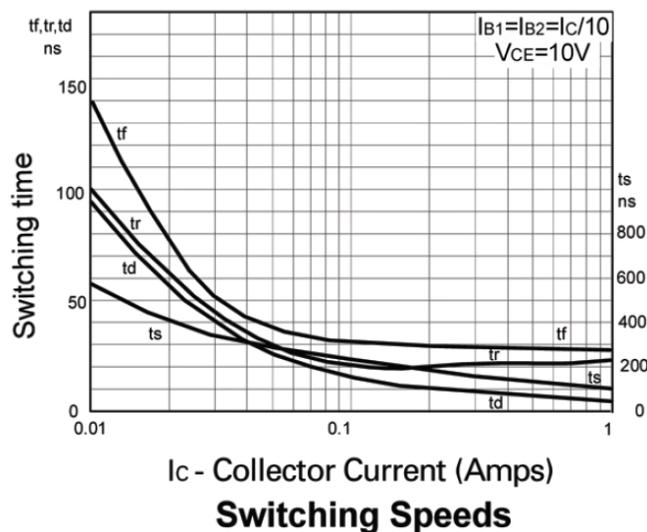
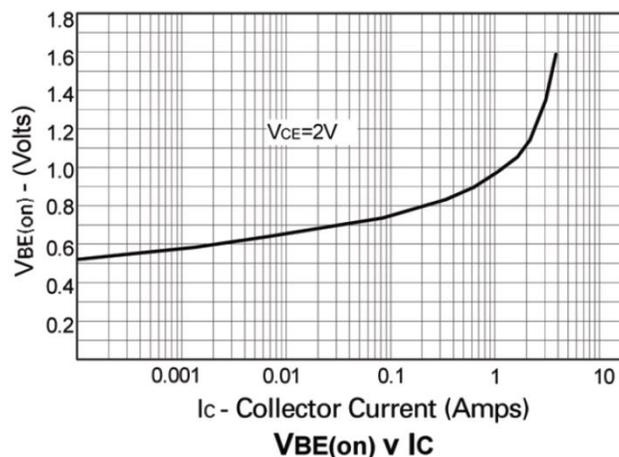
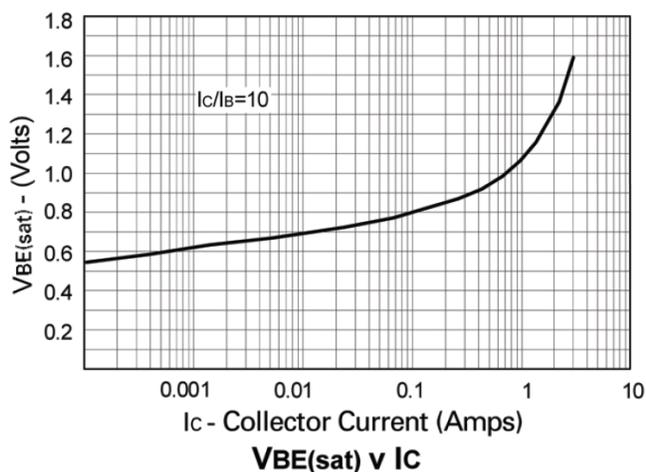
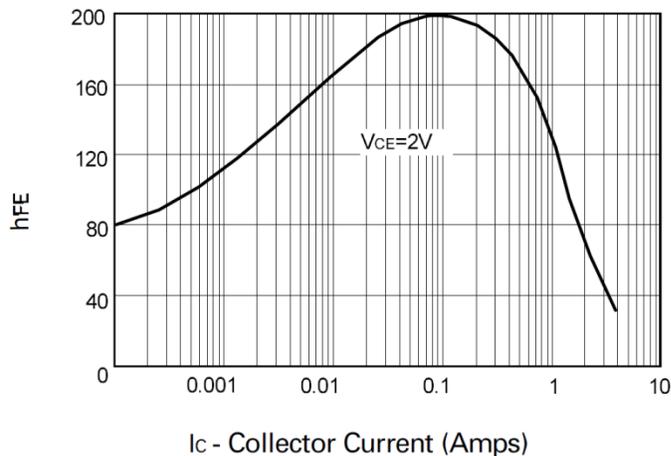
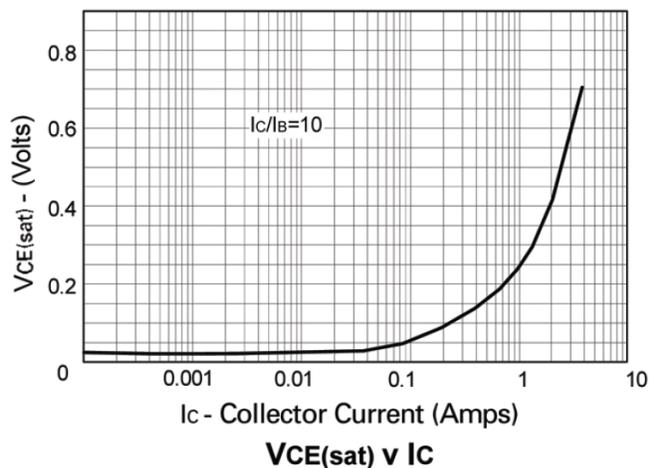
Derating Curve

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

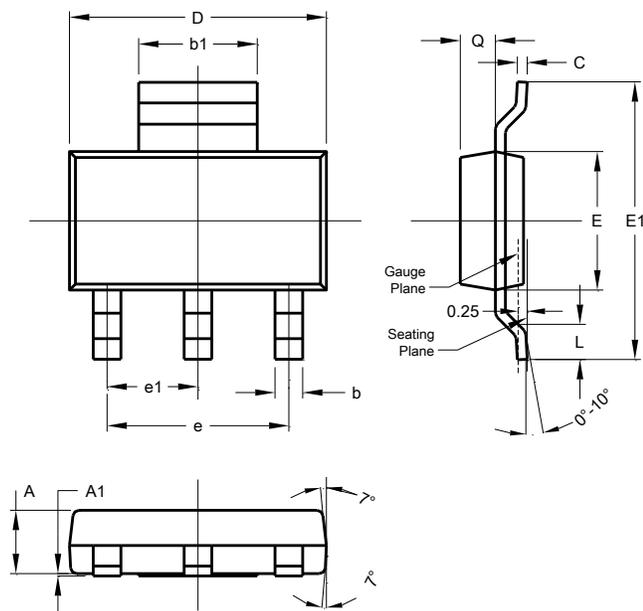
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CB0}	50	–	–	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	30	–	–	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	7	–	–	V	I _E = 100μA
Collector Cut-Off Current	I _{CB0}	–	–	100	nA	V _{CB} = 30V
Collector Cut-Off Current	I _{CES}	–	–	100	nA	V _{CE} = 30V
Emitter Cut-Off Current	I _{EBO}	–	–	100	nA	V _{EB} = 4V
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(sat)}	–	–	0.3 0.6	V	I _C = 1A, I _B = 100mA I _C = 2A, I _B = 200mA
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	–	–	1.1	V	I _C = 1A, I _B = 100mA
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	–	–	1.0	V	I _C = 1A, V _{CE} = 2V
DC Current Gain (Note 12)	h _{FE}	100 100 60 20	– – – –	– 300 – –	–	I _C = 1mA, V _{CE} = 2V I _C = 1A, V _{CE} = 2V I _C = 2A, V _{CE} = 2V I _C = 4A, V _{CE} = 2V
Current Gain-Bandwidth Product	f _T	150	–	–	MHz	V _{CE} = 10V, I _C = 50mA f = 100MHz
Output Capacitance	C _{obo}	–	–	10	pF	V _{CB} = 10V, f = 1MHz

Note: 12. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

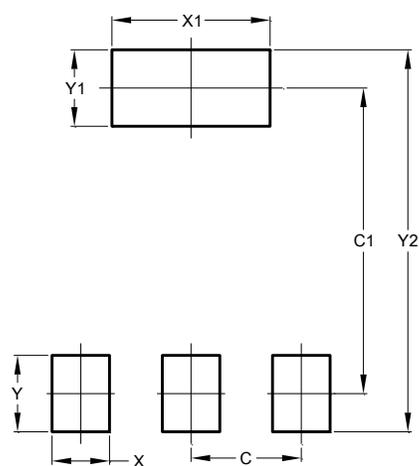


Package Outline Dimensions



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00